TMN6050Y

N-Channel Enhancement Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

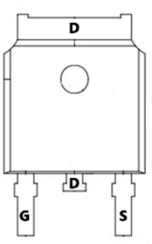
- Load switch
- PWM

General Features

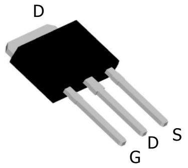
V_{DS} = 60V I_D =50A

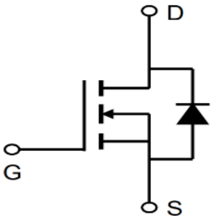
$R_{DS(ON)}$=13 mΩ (typ.)@ V_{GS}=10V

100% UIS Tested
100% R_g Tested



Y:TO-251S-3L





Marking: 50N06

Absolute Maximum Ratings (T_A= 25°C unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25℃	50	A
		T_C = 100℃	23	A
I_{DM}	Pulsed Drain Current note1		180	A
EAS	Single Pulsed Avalanche Energy note2		280	mJ
P_D	Power Dissipation	T_C = 25℃	87.7	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.6	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case(Note 2)	$R_{\theta JC}$	1.76	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1.0	1.6	2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=30A	-	13	16	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=30A	30	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=25V,V_{GS}=0V, F=1.0MHz	-	2498	-	PF
Output Capacitance	C_{oss}		-	185	-	PF
Reverse Transfer Capacitance	C_{rss}		-	80	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V,I_D=2A,R_L=1Ω V_{GS}=10V,R_{GEN}=3Ω	-	12	-	nS
Turn-on Rise Time	t_r		-	5.2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	38	-	nS
Turn-Off Fall Time	t_f		-	27	-	nS
Total Gate Charge	Q_g	V_{DS}=30V,I_D=30A, V_{GS}=10V	-	36	-	nC
Gate-Source Charge	Q_{gs}		-	9.9	-	nC
Gate-Drain Charge	Q_{gd}		-	6.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=30A	-	-	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	50	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, IF =30A di/dt = 100A/μs (Note3)	-	35		nS
Reverse Recovery Charge	Qrr		-	47		nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: Tj=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω

Typical Performance Characteristics

Figure1: Output Characteristics

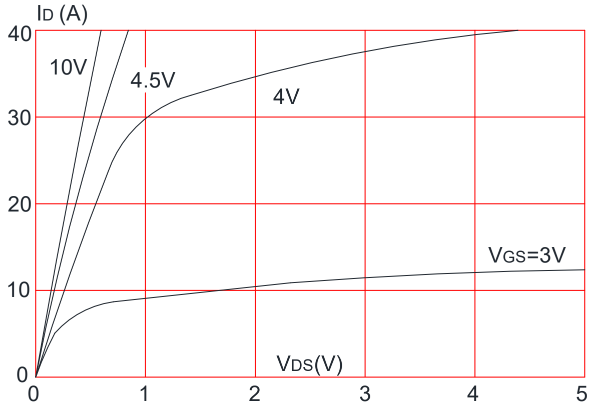


Figure 2: Typical Transfer Characteristics

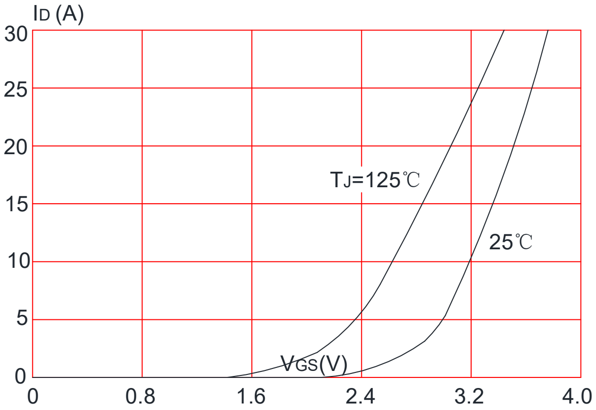


Figure 3: On-resistance vs. Drain Current

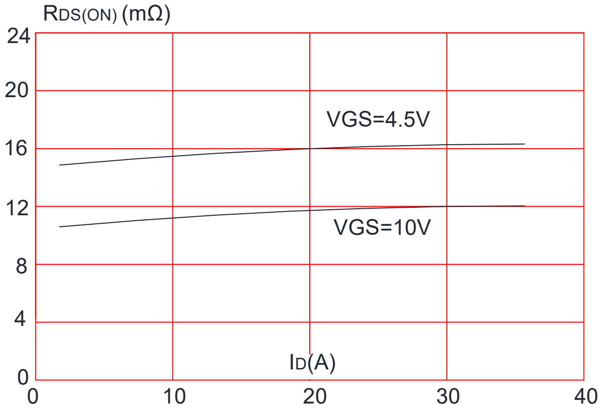


Figure 4: Body Diode Characteristics

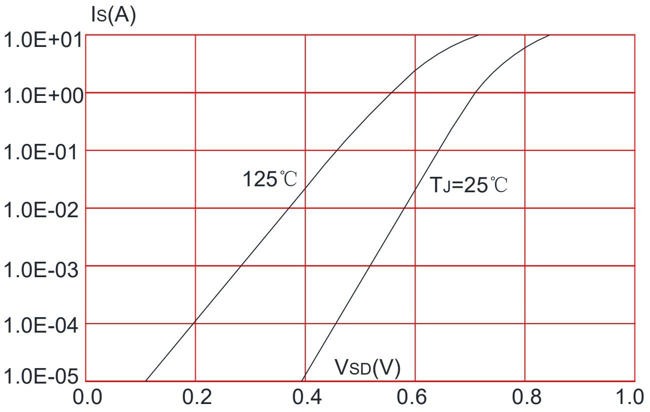


Figure 5: Gate Charge Characteristics

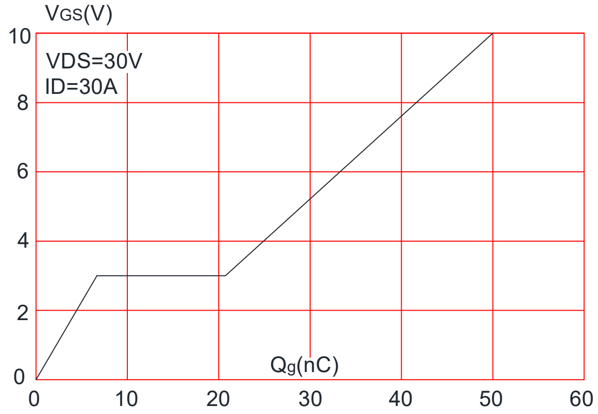


Figure 6: Capacitance Characteristics

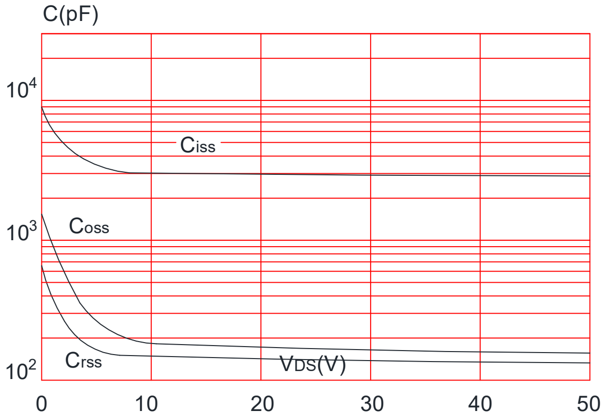


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

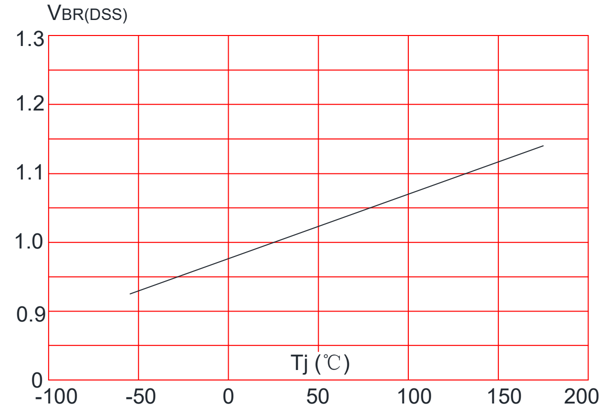


Figure 8: Normalized on Resistance vs. Junction Temperature

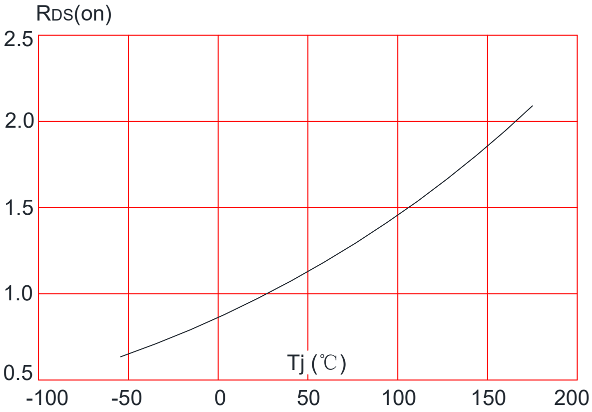


Figure 9: Maximum Safe Operating Area

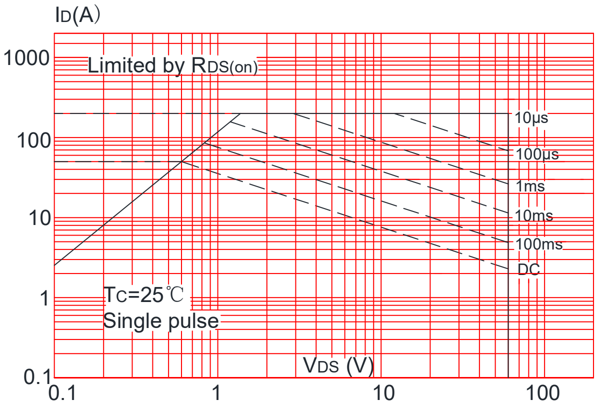


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

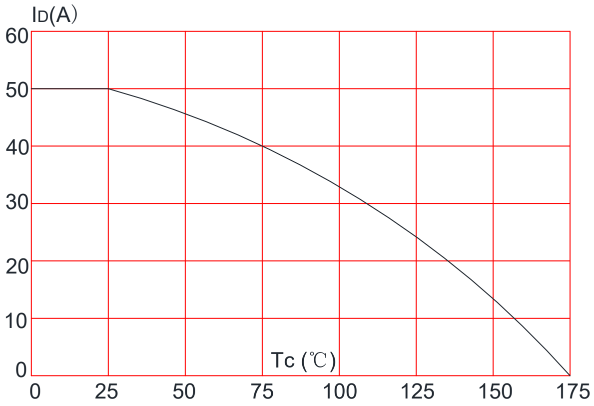
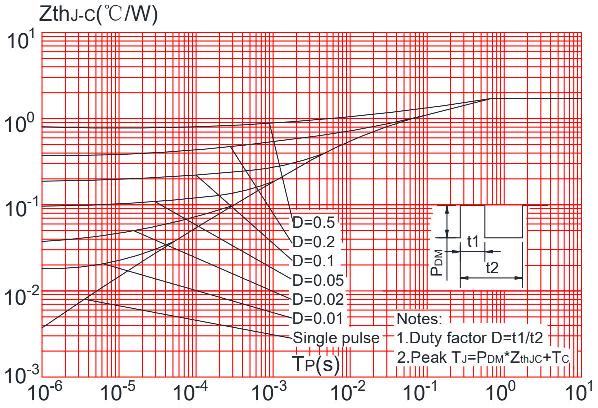


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Package Information:TO-251S-3L

UNIT：mm

SYMBOL	min	nom	max
A	2.20		2.40
b	0.50		0.85
C	0.45	0.50	0.60
D	6.50		6.70
D1	5.10		5.50
E	5.9		6.20
e	2.18	2.29	2.38
L	11.00		12.40
L1	4.8		5.3
L2	3.5		4.2